

S/N 09/854539

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Steven Towle, Deceased

Examiner: Ginette Peralta

Serial No.: 09/854539

Group Art Unit: 2814

Filed: May 14, 2001

Docket No.: 884.415US1

Title: POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR  
USE IN MICROELECTRONIC CIRCUIT PACKAGING

Assignee: Intel Corporation

Customer No.: 21186

RESPONSE UNDER 37 CFR § 1.111

MS Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

PRELIMINARY REMARKS

Applicant's attorneys of record are saddened to communicate with the Office that Applicant, Steven Towle is deceased. The Assignee of this patent application, acting under authority of 37 C.F.R. §3.73(b) and (c) will re-appointed Applicant's attorneys to prosecute this patent application. Such reappointment will be submitted in a timely manner. Accordingly, the Assignee will appear henceforth as the Applicant.

Applicant, by his Assignee (hereinafter "Applicant"), has reviewed the Office Action mailed on May 8, 2003. Please consider this response to the above-identified patent application as follows.

